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Yilmaz et al.(10) **Pub. No.: US 2014/0054758 A1**(43) **Pub. Date: Feb. 27, 2014**(54) **STACKED DUAL CHIP PACKAGE HAVING
LEVELING PROJECTIONS**(22) Filed: **Nov. 4, 2013****Related U.S. Application Data**(71) Applicant: **Alpha and Omega Semiconductor
Incorporated**, Sunnyvale, CA (US)(63) Continuation of application No. 12/819,111, filed on
Jun. 18, 2010, now Pat. No. 8,581,376.(72) Inventors: **Hamza Yilmaz**, Saratoga, CA (US);
Xiaotian Zhang, San Jose, CA (US);
Yan Xun Xue, Los Gatos, CA (US);
Anup Bhalla, Santa Clara, CA (US);
Jun Lu, San Jose, CA (US); **Kai Liu**,
Mountain View, CA (US); **Yueh-Se So**,
Sunnyvale, CA (US); **John Amato**,
Tracy, CA (US)**Publication Classification**(51) **Int. Cl.**
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USPC **257/669**(73) Assignee: **ALPHA AND OMEGA
SEMICONDUCTOR
INCORPORATED**, Sunnyvale, CA
(US)(57) **ABSTRACT**

The present invention is directed to a lead-frame having a stack of semiconductor dies with interposed metalized clip structure. Level projections extend from the clip structure to ensure that the clip structure remains level during fabrication.

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